Intelligent Power Module (IPM) 650 V, 20 A

NFAM2065L4BT

General Description

The NFAM2065L4BT is a fully-integrated inverter power module consisting of an independent High side gate driver, LVIC, six IGBT's and a temperature sensor (VTS or Thermistor(T)), suitable for driving permanent magnet synchronous (PMSM) motors, brushless DC (BLDC) motors and AC asynchronous motors. The IGBT's are configured in a three-phase bridge with separate emitter connections for the lower legs for maximum flexibility in the choice of control algorithm.

The power stage has under-voltage lockout protection (UVP). Internal boost diodes are provided for high side gate boost drive.

Features

- Three–phase 650 V, 20 A IGBT Module with Independent Drivers
- Active Logic Interface
- Built-in Under-voltage Protection (UVP)
- Integrated Bootstrap Diodes and Resistors
- Separate Low-side IGBT Emitter Connections for Individual Current Sensing of Each Phase
- Temperature Sensor (VTS or Thermistor (T))
- UL1557 Certified (File No.E339285)
- This is a Pb-Free Device

Typical Application

- Industrial Drives
- Industrial Pumps
- Industrial Fans
- Industrial Automation

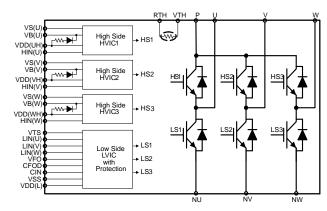
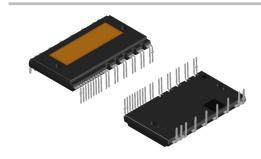


Figure 1. Application Schematic



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DIP39 54.5 x 31.0 CASE MODGC

MARKING DIAGRAM

O NFAM2065L4BT O ZZZATYWW

Device marking is on package top side

NFAM2065L4BT = Specific Device Code
ZZZ = Assembly Lot Code
A = Assembly Location
T = Test Location
Y = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
NFAM2065L4BT	DIP39, 31.0x54.5 (Pb-Free)	90 / BOX

APPLICATION SCHEMATIC

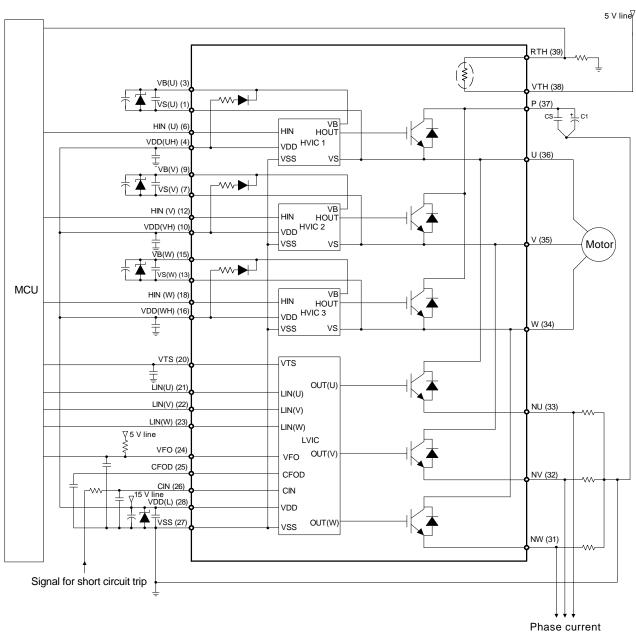


Figure 2. Application Schematic - Adjustable Option

BLOCK DIAGRAM

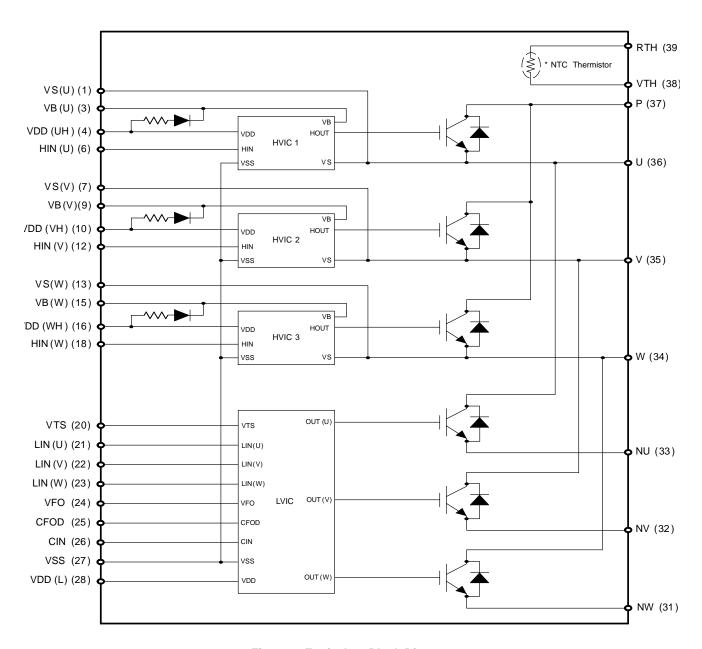


Figure 3. Equivalent Block Diagram

PIN FUNCTION DESCRIPTION

Pin	Name	Description
1	VS(U)	High-Side Bias Voltage GND for U Phase IGBT Driving
(2)	-	Dummy
3	VB(U)	High-Side Bias Voltage for U Phase IGBT Driving
4	VDD(UH)	High-Side Bias Voltage for U Phase IC
(5)	-	Dummy
6	HIN(U)	Signal Input for High-Side U Phase
7	VS(V)	High-Side Bias Voltage GND for V Phase IGBT Driving
(8)	-	Dummy
9	VB(V)	High-Side Bias Voltage for V Phase IGBT Driving
10	VDD(VH)	High-Side Bias Voltage for V Phase IC
(11)	-	Dummy
12	HIN(V)	Signal Input for High–Side V Phase
13	VS(W)	High-Side Bias Voltage GND for W Phase IGBT Driving
(14)	-	Dummy
15	VB(W)	High-Side Bias Voltage for W Phase IGBT Driving
16	VDD(WH)	High-Side Bias Voltage for W Phase IC
(17)	-	Dummy
18	HIN(W)	Signal Input for High–Side W Phase
(19)	-	Dummy
20	VTS	Voltage Output for LVIC Temperature Sensing Unit
21	LIN(U)	Signal Input for Low–Side U Phase
22	LIN(V)	Signal Input for Low–Side V Phase
23	LIN(W)	Signal Input for Low–Side W Phase
24	VFO	Fault Output
25	CFOD	Capacitor for Fault Output Duration Selection
26	CIN	Input for Current Protection
27	VSS	Low-Side Common Supply Ground
28	VDD(L)	Low-Side Bias Voltage for IC and IGBTs Driving
(29)	-	Dummy
(30)	-	Dummy
31	NW	Negative DC-Link Input for U Phase
32	NV	Negative DC-Link Input for V Phase
33	NU	Negative DC-Link Input for W Phase
34	W	Output for U Phase
35	V	Output for V Phase
36	U	Output for W Phase
37	Р	Positive DC-Link Input
38	VTH	Thermistor Bias Voltage (T) / Not connection
39	RTH	Series Resister for Thermistor (Temperature Detection) *optional for T

^{1.} Pins of () are the dummy for internal connection. These pins should be no connection.

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C) (Note 2)

Rating	Symbol	Conditions	Value	Unit
Supply Voltage	VPN	P – NU, NV, NW	450	V
Supply Voltage (Surge)	VPN(Surge)	P – NU, NV, NW, (Note 3)	550	V
Self Protection Supply Voltage Limit (Short–Circuit Protection Capability)	VPN(PROT)	VDD = VBS = 13.5 V ~ 16.5 V, Tj = 150°C, Vces < 650 V, Non–Repetitive, < 2 us	400	V
Collector–Emitter Voltage	Vces		650	V
Maximum Repetitive Revers Voltage	VRRM		650	V
Each IGBT Collector Current	±lc		±20	Α
Each IGBT Collector Current (Peak)	±lcp	Under 1 ms Pulse Width	±40	Α
Control Supply Voltage	VDD	VDD(UH,VH,WH), VDD(L) – VSS	-0.3 to 20	V
High-Side Control Bias Voltage	VBS	VB(U) - VS(U), VB(V) - VS(V), VB(W) - VS(W)	-0.3 to 20	V
Input Signal Voltage	VIN	HIN(U), HIN(V), HIN(W), LIN(U), LIN(V), LIN(W) – VSS	-0.3 to VDD	V
Fault Output Supply Voltage	VFO	VFO – VSS	-0.3 to VDD	V
Fault Output Current	IFO	Sink Current at VFO pin	2	mA
Current Sensing Input Voltage	VCIN	CIN - VSS	-0.3 to VDD	V
Corrector Dissipation	Pc	Per One Chip	96	W
Operating Junction Temperature	Tj		-40 to +150	°C
Storage Temperature	Tstg		-40 to +125	°C
Module Case Operation Temperature	Tc		-40 to +125	°C
Isolation Voltage	Viso	60 Hz, Sinusoidal, AC 1 minute, Connection Pins to Heat Sink Plate	2500	V rms

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Rating	Symbol	Conditions	Min	Тур	Max	Unit
Junction to Case Thermal	Rth(j-c)Q	Inverter IGBT Part (per 1/6 Module)	-	-	1.3	°C/W
Resistance	Rth(j-c)F	Inverter FWDi Part (per 1/6 Module)	_	_	2.4	°C/W

^{4.} Refer to ELECTRICAL CHARACTERISTICS, RECOMMENDED OPERATING RANGES and/or APPLICATION INFORMATION for Safe Operating parameters.

RECOMMENDED OPERATING RANGES (Note 5)

Rating	Symbol	Conditions	Conditions		Тур	Max	Unit
Supply Voltage	VPN	P – NU, NV, NW		-	300	400	V
Gate Driver Supply Voltages	VDD	VDD(UH,VH,WH), VDD(L) – VSS	13.5	15	16.5	V
	VBS	VB(U) - VS(U), VB(V) - VS(V), VB(W) - VS(W)		13.0	15	18.5	V
Supply Voltage Variation	dVDD / dt dVBS / dt			-1	-	1	V/μs
PWM Frequency	fPWM			1		20	kHz
Dead Time	DT	Turn-off to Turn-on (exter	Turn-off to Turn-on (external)		_	-	μS
Allowable r.m.s. Current	lo	VPN = 300 V, VDD = VD = 15 V,	fPWM = 5 kHz	-	-	20.5	A rms
	P.F. = 0.8, Tc ≤ 125°C, Tj ≤ 150°C, (Note 5)	fPWM = 15 kHz	1	-	15.4		

Refer to ELECTRICAL CHARACTERISTICS, RECOMMENDED OPERATING RANGES and/or APPLICATION INFORMATION for Safe Operating parameters.

^{3.} This surge voltage developed by the switching operation due to the wiring inductance between P and NU, NV, NW terminal.

RECOMMENDED OPERATING RANGES (Note 5) (continued)

Rating	Symbol	Conditions	Min	Тур	Max	Unit
Allowable Input Pulse Width	PWIN (on)	200 V ≤ VPN ≤ 400 V, 13.5 V ≤ VDD ≤ 16.5 V,	1.0	-	-	μS
	PWIN (off)	13.0 V ≤ VBS ≤ 18.5 V, -20°C ≤ Tc ≤ 100°C	1.5	-	-	
Package Mounting Torque		M3 Type Screw	0.6	0.7	0.9	Nm

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

5. Allowable r.m.s Current depends on the actual conditions.

- 6. Flatness tolerance of the heatsink should be within –50 μ m to +100 μ m.

ELECTRICAL CHARACTERISTICS (Tc = 25°C, VDD = 15 V, VBS = 15 V, unless otherwise noted) (Note 7)

Pa	arameter	Test Conditions	Symbol	Min	Тур	Max	Unit	
INVERTER S	SECTION			•	_	_	_	•
	nitter Leakage	Vce = Vces, Tj = 25°C		Ices	_	_	1	mA
Current		Vce = Vces, Tj = 150°C			_	-	10	mA
Collector-Em Voltage	nitter Saturation	VDD = VBS = 15 V, IN = 5 V Ic = 20 A, Tj = 25°C		VCE(sat)	-	1.60	2.30	V
		VDD = VBS = 15 V, IN = 5 V Ic = 20 A, Tj = 150°C			-	1.80	-	V
FWDi Forwar	d Voltage	IN = 0 V, If = 20 A, Tj = 25°C		VF	-	1.90	2.30	V
		IN = 0 V, If = 20 A, Tj = 150°C		1	_	1.90	-	V
High Side	Switching Times	VPN = 300 V, VDD(H) = VDD(L) =	15 V	ton	0.80	1.30	1.90	μS
		Ic = 20 A, Tj = 25°C, \dot{IN} = 0 \Leftrightarrow 5 V Inductive Load		tc (on)	-	0.20	0.60	μS
				toff	-	1.40	2.00	μS
				tc (off)	-	0.20	0.70	μS
			trr	-	0.15	-	μS	
Low Side	Switching Times	VPN = 300 V, VDD(H) = VDD(L) =	ton	0.80	1.40	2.00	μS	
		Ic = 20 A, Tj = 25°C, IN = 0 ⇔ 5 V Inductive Load	Ic = 20 A, Tj = 25 $^{\circ}$ C, IN = 0 \Leftrightarrow 5 V Inductive Load		-	0.20	0.60	μS
				toff	_	1.50	2.10	μS
				tc (off)	_	0.20	0.70	μs
			trr	_	0.15	-	μs	
DRIVER SEC	CTION	•		•				
Quiescent VDD Supply Current		VDD(UH,VH,WH) = 15 V, HIN(U,V,W) = 0 V	VDD(UH) – VSS VDD(VH) – VSS VDD(WH) – VSS	IQDDH	-	-	0.30	mA
		VDD(L) = 15 V, LIN(U, V, W) = 0 V	VDD(L) – VSS	IQDDL	-	-	3.50	mA
Operating VDD Supply Current		VDD(UH, VH, WH) = 15 V, fPWM = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for High–Side	fPWM = 20 kHz, Duty = 50%, Applied to one PWM Signal Input VDD(VH) – VSS		-	-	0.40	mA
		VDD(L) = 15 V, fPWM = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for Low–Side	VDD(L) - VSS	IPDDL	-	-	6.00	mA
Quiescent VBS Supply Current		VB(U) - VS(U) VB(V) - VS(V) VB(W) - VS(W)	IQBS	-	-	0.30	mA	

ELECTRICAL CHARACTERISTICS (Tc = 25°C, VDD = 15 V, VBS = 15 V, unless otherwise noted) (Note 7) (continued)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit	
DRIVER SECTION			•		•	•	
Operating VBS Supply Current	VDD = VBS = 15 V, fPWM = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for High-Side	VB(U) - VS(U) VB(V) - VS(V) VB(W) - VS(W)	IPBS	-	-	5.00	mA
ON Threshold Voltage	HIN(U, V, W) – VSS, LIN(U, V, W)	– VSS	VIN(ON)	-	_	2.6	V
OFF Threshold Voltage			VIN(OF)	0.8	-	_	V
Short Circuit Trip Level	VDD = 15 V, CIN-VSS	VDD = 15 V, CIN-VSS		0.46	0.48	0.50	V
Supply Circuit Under-Voltage	Detection Level		UVDDD	10.3	-	12.5	V
Protection	Reset Level		UVDDR	10.8	_	13.0	V
	Detection Level		UVBSD	10.0	-	12.0	V
	Reset Level	UVBSR	10.5	_	12.5	V	
Voltage Output for LVIC Temperature Sensing Unit	VTS-VSS = 10 nF, Temp. = 25°C	VTS-VSS = 10 nF, Temp. = 25°C		0.905	1.030	1.155	V
Fault Output Voltage	It Output Voltage $ VDD = 0 \text{ V, CIN} = 0 \text{ V,} $ $ VFO \text{ Circuit: } 10 \text{ k}\Omega \text{ to 5 V Pull-up} $		VFOH	4.9	-	-	V
	VDD = 0 V, CIN = 1 V, VFO Circuit: 10 kΩ to 5 V Pull–up		VFOL	-	_	0.95	V
Fault-Output Pulse Width	CFOD = 22 nF		tFOD	1.6	2.4	_	ms
BOOTSTRAP SECTION							
Bootstrap Diode Forward Voltage	If = 0.1 A		VF	3.4	4.6	5.8	V
Built-in Limiting Resistance			RBOOT	30	38	46	Ω

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 7. Performance guaranteed over the indicated operating temperature range by design and/or characterization tested at T_J = T_A = 25°C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.
- 8. The fault—out pulse width tFOD depends on the capacitance value of CFOD according to the following approximate equation: tFOD = 0.1 x 10⁶ x CFOD (s).
- 9. Values based on design and/or characterization.

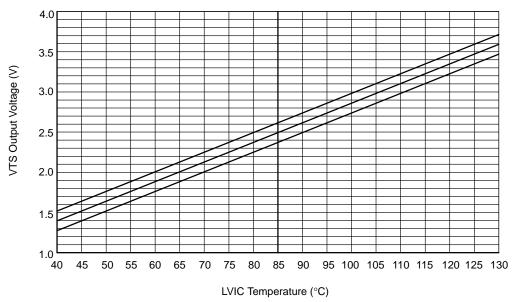


Figure 4. Temperature of LVIC versus VOT Characteristics

THERMISTOR CHARACTERISTIC

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Resistance	R ₂₅	Tc = 25°C	46.530	47	47.47	kΩ
Resistance	R ₁₂₅	Tc = 100°C	1.344	1.406	1.471	kΩ
B-Constant (25-50°C)	-	В	4009.5	4050	4090.5	K
Temperature Range	1	-	-40	1	+125	°C

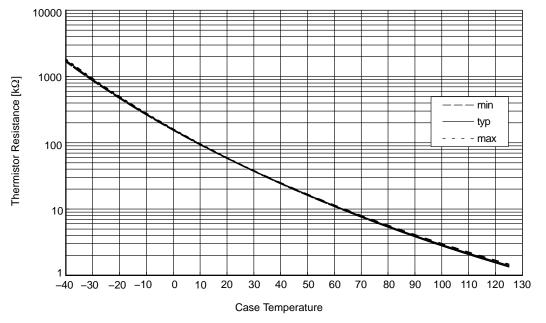


Figure 5. Thermistor Resistance versus Case Temperature



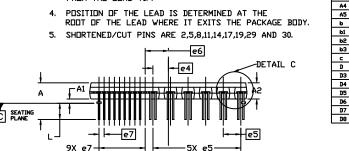
MINI DIP39, 31.0x54.5 **CASE MODGC ISSUE A**

DATE 19 MAR 2019

E2 **E3**

NOTES

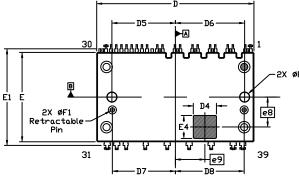
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- ASML Y14.3M, 2009.
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 FROM THE LEAD TIP.

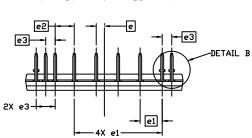


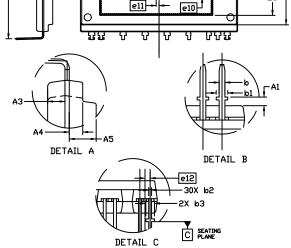
A 1220 12.7 13. A1 1.00 1.50 2.0 A2 5.50 5.60 5.7 A3 2.00 REF A4 1.55 REF A5 3.10 REF b 0.90 1.00 1.1 b1 1.90 2.00 2.1 b2 0.40 0.50 0.6 b3 1.40 1.50 REF c 0.50 REF		MILLIMETERS			
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A2 5.50 5.60 5.7 A3 2.00 REF A4 1.55 REF B 0.90 1.00 1.1 B1 1.90 2.00 2.1 B2 0.40 0.50 0.6 B3 1.40 1.50 1.6 C 0.50 REF D 54.40 54.50 54.6 B3 39.25 REF D 3 39.25 REF D 8.00 REF	A	12.20	12.7	13.2	
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A4 1.55 REF A5 3.10 REF b 0.90 1.00 1.11 bit 1.90 2.00 2.1 b2 0.40 0.50 0.6 b3 1.40 1.50 1.6 c 0.50 REF D 54.40 54.50 54.40 D3 39.25 REF D4 8.00 REF	A2	5.50	5.60	5.70	
A5 3.10 REF b 0.90 1.00 1.11 b1 1.90 2.00 2.1 b2 0.40 0.50 0.6 b3 1.40 1.50 1.6 c 0.50 REF D 54.40 54.0 54.0 54.0 D3 39.25 REF D4 8.00 REF	A3		2.00 REF		
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b1 1.90 2.00 2.1 b2 0.40 0.50 0.6 b3 1.40 1.50 1.6 c 0.50 REF D 54.40 54.50 54.4 D3 39.25 REF D4 8.00 REF	A5		3.10 REF		
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b3 1.40 1.50 1.6 c 0.50 REF D 54.40 54.50 54.4 D3 39.25 REF D4 8.00 REF	lo1	1.90	2.00	2.10	
C 0.50 REF D 54.40 54.50 54.6 D3 39.25 REF D4 8.00 REF	b2	0.40	0.50	0.60	
D 54.40 54.50 54.6 D3 39.25 REF D4 8.00 REF	b3	1.40	1.50	1.60	
D3 39.25 REF D4 8.00 REF	c		0.50 REF		
D4 8.00 REF	D	54.40	54.50	54.60	
	D3		9.25 RE	F	
D5 22.00 REF	D4		8.00 REF	•	
	D5		22.00 RE	F	
D6 24.00 REF	D6	24.00 REF			
D7 21.85 REF	D7	í	21.85 RE	F	
D8 23.85 REF	D8	- E	3.85 RE	F	

DETAIL A

	MILLIMETERS					
DIM	MIN.	NDM.	MAX.			
Ε	30.90	31.00	31.10			
E1		3.50 RE	F			
E2	ű	26.14 REI	-1			
E3	1	2.35 REI	F			
E4		8.00 REF				
E5	35.40	35.90	36.40			
e		2.81 REF				
e1	7.62 BSC					
e2	6.60 BSC					
e3	3.30 BSC					
e4	5.35 REF					
e5	6.10 BSC					
e6		8.02 REF				
e7		1.78 BSC	:			
e8	_	0.35 REI				
e9		10.25 REF				
e10	3.60 REF					
e11	1.00 REF					
e12	0.89 BSC					
F	3.20	3.30	3.40			
F1	1.40	1.50	1.60			
L		5.60 REF				







GENERIC MARKING DIAGRAM*

XXXXXXXXXXXXXXXXX **ZZZATYWW**

XXXXX = Specific Device Code

= Assembly Lot Code

ΑT = Assembly & Test Location = Year = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " • ", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON91300G	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED"	
DESCRIPTION:	MINI DIP39, 31.0x54.5		PAGE 1 OF 1

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